

AN 2000:342333 HCAPLUS  
 DN 132:337980  
 TI Lead-free solder of **tin**-aluminum-**indium**-**silver**  
 alloy for low temperature use  
 IN Domi, Shinjiro; Sakaguchi, Koichi; Nakagaki, Shigeki; Suganuma, Katsuaki  
 PA Nippon Sheet Glass Co., Ltd., Japan  
 SO Jpn. Kokai Tokkyo Koho, 5 pp.  
 CODEN: JKXXAF  
 DT Patent  
 LA Japanese  
 FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 2000141078	A2	20000523	JP 1999-54716	19990302
PRAI	JP 1998-253852	A	19980908		
AB	The solder of <b>Sn</b> alloy contains Al 0.01-3.0, In 0.1-50, <b>Ag</b> 0.1-6.0, <b>Cu</b> 0-6.0, and Zn 0-10.0%. Oxide materials, e.g., glasses, ceramics, can be strongly bonded with the solder.				